Application Data Sheet

Application Information

Application Type::

Regular

Subject Matter::

Utility

Suggested Classification::

Suggested Group Art Unit::

CD-ROM or CD_R?::

None

Number of CD disks::

Number of copies of CDs::

Sequence Submission::

No

Computer Readable Form (CRF)?::

No

Title::

SEMICONDUCTOR DEVICE AND METHOD OF

MANUFACTURING THE SAME

Attorney Docket Number::

10873.1303US01

Request For Early Publication::

No

Request For Non-Publication::

No

Suggested Drawing Figure::

1A

Total Drawing Sheets::

11

Small Entity::

No

Latin Name::

Variety Denomination Name::

Petition Included::

No

Petition Type::

Licensed US Govt. Agency::

Contract or Grant Numbers::

Secrecy Order in Parent Appl.?::

No

Applicant Information

Applicant Authority Type:: Inventor

Primary Citizenship Country:: Japan

Status:: Full Capacity

Given Name:: Akira

Middle Name::

Family Name:: FUKUMOTO

Name Suffix::

City of Residence:: Hirakata-shi

State or Province of Residence:: Osaka

Country of Residence:: Japan

Street of mailing address:: 2-15-20-304, Nasuzukuri

City of mailing address:: Hirakata-shi

State or Province of mailing address:: Osaka

Country of mailing address:: Japan

Postal or Zip Code of mailing address:: 573-0071

Correspondence Information

Correspondence Customer Number:: 23552

Representative Information

Representative Customer Number::	23552

Foreign Priority Information

Country::	Application Number::	Filing Date::	Priority Claimed::
Japan	2002-297982	October 10, 2002	Yes

Assignee Information

Assignee Name:: MATSUSHITA ELECTRIC INDUSTRIAL CO.,

LTD.

Street of mailing address:: 1006, Oaza Kadoma

City of mailing address:: Kadoma-shi

State or Province of mailing address:: Osaka

Country of mailing address:: Japan

Postal or Zip Code of mailing address:: 571-8501